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ASX RELEASE

17 July 2019

4DS CLOSES A\$3.25 MILLION PLACEMENT & LAUNCHES A\$0.75 MILLION SPP

- A\$3.25 million Placement will fund development activities to achieve key strategic and technical milestones with imec
- Placement was well supported by existing and new professional and sophisticated investors
- The Company is also undertaking an SPP for up to A\$750,000

Share Placement

4DS Memory Limited (ASX:4DS) (**4DS** or the **Company**) today announced the successful closure of a placement of 65 million new ordinary shares at an issue price of A\$0.05 per share to professional and sophisticated investors to raise A\$3.25 million (**Placement**). The new shares will be issued, within the Company's 15% placement capacity, on or around Monday, 22 July 2019.

Share Purchase Plan

4DS is also undertaking a Share Purchase Plan (**SPP**), providing existing eligible shareholders with the opportunity to subscribe for up to a maximum of A\$15,000 worth of 4DS ordinary shares at a purchase price of \$0.05 per share, being the same issue price as for the Placement. The total amount to be raised under the SPP will be **capped at A\$750,000**. Eligible shareholders are shareholders whose registered address is in Australia or New Zealand as at 5.00pm on the Record Date of 16 July 2019.

Full details of the SPP will be set out in the SPP Offer Document to be sent to shareholders in the coming days. The SPP shares will be allocated on a **first-come first-served** basis, and therefore the Company encourages shareholders who wish to participate to act promptly in submitting their application forms. The timetable below is indicative only and 4DS may, at its discretion, vary the dates (including closing the SPP early) by lodging a revised timetable with the ASX.

SPP Indicative Timetable

SPP Eligibility Record Date	16 July 2019
Dispatch of SPP Offer Document	19 July 2019
Opening Date	19 July 2019
Closing Date (5.00pm WST)	2 August 2019
Allotment of SPP Shares	6 August 2019
Commencement of Trading of SPP Shares	12 August 2019

Use of Funds

If the SPP is fully subscribed, the total capital raised by 4DS (inclusive of the Placement) will be A\$4 million.

The proceeds from the Placement and the SPP will be used to fund the Company's ongoing development activities relating to its Interface Switching ReRAM for Storage Class Memory and to achieve key strategic and technical milestones with imec.



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As announced on 20 June 2019, the next iteration of 300mm wafers (**Lot 4**) will comprise of process condition variations to wafer D10 Lot 3. The processing of Lot 4 has commenced on imec's state-of-the-art production equipment. Lot 4 will comprise of two sets of twenty three 300mm wafers (46 in total), that will be processed and analysed in parallel, thereby expediting the transition to imec's 1 megabit memory platform.

The objective of Lot 4 will be to further optimise speed, endurance and retention, with the results of the analysis of Lot 4 expected during Q3 of 2019. This optimisation is a required and logical step before the Company integrates its technology onto imec's 1 megabit memory platform, potentially after the completion of the analysis of Lot 4. In turn, this brings the Company closer to its goal of ultimately being able to produce a 1 megabit memory chip.

Forrest Capital acted as the lead manager and CPS Securities as co-manager to the Placement.

ENDS

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About 4DS

4DS Memory Limited (ASX: 4DS), with facilities located in Silicon Valley, is a semiconductor development company of non-volatile memory technology, pioneering Interface Switching ReRAM for next generation gigabyte storage in mobile and cloud. Established in 2007, 4DS owns a patented IP portfolio, comprising 20 US patents granted and 10 patents pending and or filed, which has been developed in-house to create high-density Storage Class Memory. 4DS has a joint development agreement with Western Digital subsidiary HGST, a global storage leader, which accelerates the evolution of 4DS' technology. 4DS also collaborates with imec, a world-leading research and innovation hub in nanoelectronics and digital technologies. The combination of imec's widely acclaimed leadership in microchip technology and profound software and information and communication technology expertise makes them unique.

For more information, please visit <u>www.4dsmemory.com</u>.

Disclaimer

You should not place undue reliance on these forward- looking statements. Except as required by law or regulation (including the ASX Listing Rules) we undertake no obligation to update these forward- looking statements.

This release contains certain forward looking statements that are based on the Company's management's beliefs, assumptions and expectations and on information currently available to management. Such forward looking statements involve known and unknown risks, uncertainties, and other factors which may cause the actual results or performance of 4DS to be materially different from the results or performance expressed or implied by such forward looking statements. Such forward looking statements are based on numerous assumptions regarding the Company's present and future business strategies and the political and economic environment in which 4DS will operate in the future, which are subject to change without notice. Past performance is not necessarily a guide to future performance and no representation or warranty is made as to the likelihood of achievement or reasonableness of any forward looking statements or other forecast. To the full extent permitted by law, 4DS and its directors, officers, employees, advisers, agents and intermediaries disclaim any obligation or undertaking to release any updates or revisions to information to reflect any change in any of the information contained in this release (including, but not limited to, any assumptions or expectations set out in the release).